


PCN Number:	20180531007	PCN Date:	June 1, 2018
Title:	Datasheet for OPA355-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		OPA355-Q1 <small>SLOS868C – DECEMBER 2013 – REVISED MAY 2018</small>	
Changes from Revision B (June 2014) to Revision C			
			Page
•	Deleted "C55" marking on pinout drawing in <i>Pin Configuration and Functions</i> section		3
•	Added Pin Functions table to <i>Pin Configuration and Functions</i> section		3
•	Deleted storage temperature range from <i>ESD Ratings</i> table and moved to <i>Absolute Maximum Ratings</i> table		4
•	Changed title of <i>Handling Ratings</i> table to <i>ESD Ratings</i> table		4
•	Added <i>Recommended Operating Conditions</i> table		4
•	Added <i>Functional Block Diagram</i>		12
•	Deleted "Independent enable pins are available for each channel, which provide maximum design flexibility" from <i>Enable Function</i> section		12
•	Deleted <i>Input and ESD Protection</i> subsection in <i>Feature Description</i> section		13
•	Added <i>Device Functional Modes</i> section		13
•	Added <i>Typical Applications</i> section to <i>Application and Implementation</i> section		14
•	Added <i>Design Requirements</i> subsection to <i>Typical Applications</i> section		14
•	Added <i>Detailed Design Procedure</i> subsection to <i>Typical Application</i> section		14
•	Added application curves to the <i>Typical Application</i> section		16
•	Added <i>High-Impedance Sensor Interface, Driving ADCs, and Active Filter</i> subsections to <i>Typical Application</i> section		16
•	Added <i>Power Supply Recommendations</i> section		19
•	Added layout example image to <i>Layout</i> section		19
The datasheet number will be changing.			
Device Family		Change From:	Change To:
OPA355-Q1		SLOS868B	SLOS868C
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/OPA355-Q1			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
OPA355QDBVRQ1			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com